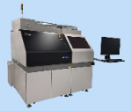
Inner Crack

Purpose	Inspect Inner Crack Defects of Sawn & Re-populated Wafer such as COG and CIS (CMOS Sensors)
Technology	1. **Optical Interference** – Inspect surface topology variation caused by internal crack/edge chipping with high speed scanning. 2. **Active Surface IR**– Inspect inner crack damages induced in sawing process by using Ultra high magnification Infrared microscopic optical solution. 3. **VISIR©™ Inspection** - Inspect die back surface using visible and infrared capable optical design. It's a See through inspection to detect inner crack damages as well as surface defects. 4. **Die Side Wall IR** - High resolution sensor combined beyond visual wavelength sensitive optical system to inspect internal cracks induced in saw cutting process

STI Products	Optical Interference	Active Surface IR	VISIR©™ Inspection	Die Side Wall IR
 **iFocus – Wafer 2D & 3D Scan**	✓	✓		
 **tSort – WLP Scan & Sort**		✓	✓	✓
 **Hexa – Tray 2D & 3D Scan**			✓	
 **tScan – 2D & 3D High Speed Scan-Pack**			✓	